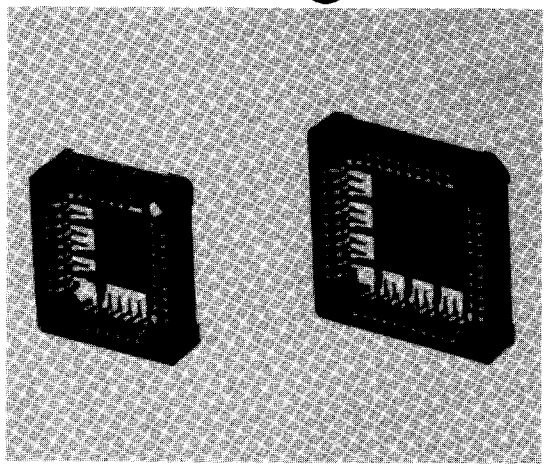
PLASTIC LEADED CHIP CARRIER

***High Density Configuration Available**



ORDERING INFORMATION

☐ –	☐ –	☐ –	☐ –	☐
1	2	3	4	5

1. DESCRIPTION
PLCC = Plastic Leaded Chip Carrier

2. POSITION
20, 28, 32, 44, 52, 68, 84, 100

3. MOUNTING ANGLE
TB = Through Board
SM = Surface Mount

4. PLATING
G = Gold over Nickel
T = Tin

5. SPECIAL OPTIONS
N = Thin wall for high density
(available in 32, 44, 68, 84)

FEATURES:

- Converts .050″ chip centers to .100″ board hole spacing
- Visual polarization for proper assembly orientation
- Closed bottom eliminates bridging and solder wicking
- Superior contact design allows proper seating and retention of JEDEC A, B and D chips

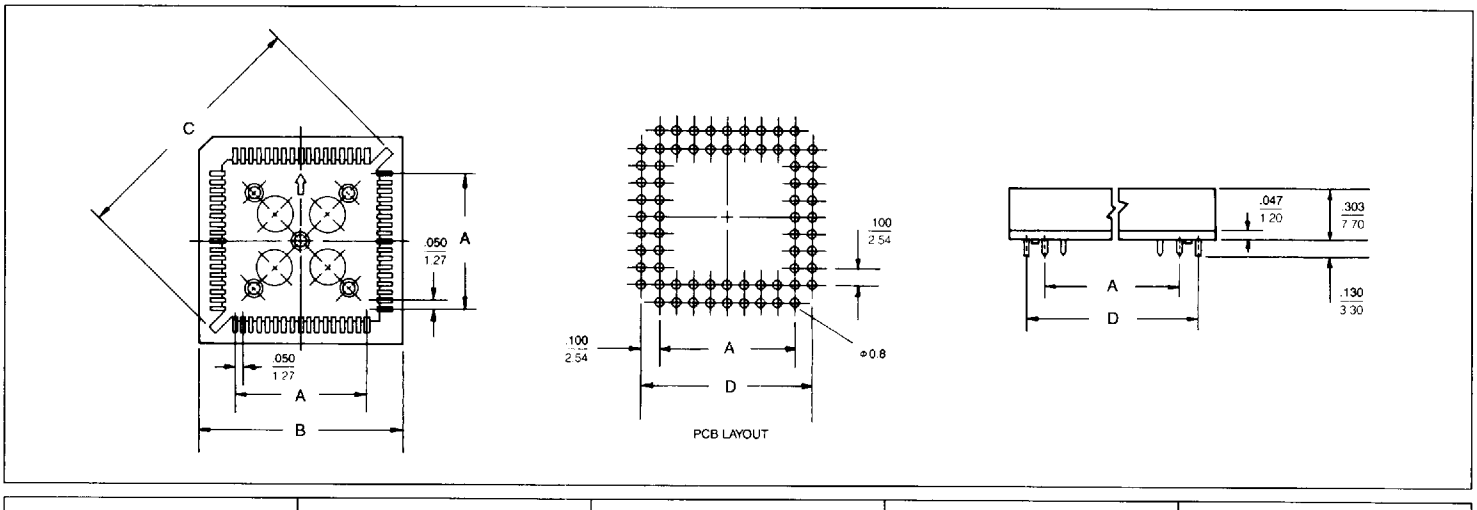
PLCC SERIES SPECIFICATIONS:

MATERIALS:	
Contacts	Phosphor Bronze
Plating	Tin or gold over nickel
Insulator	PPS high temp. UL 94V-0

ELECTRICAL:	
Current Rating	1 Amp DC
Dielectric withstanding voltage:	1000 VAC
Insulation Resistance	1000 megohms min.
Contact Resistance	5 milliohms typ. 20 max.
Operating Temperature	-65 to + 110 C

DIMENSIONAL DATA

All dimensions in (inches) and millimeters.



No. of Contact Pos.	A	B	C	D
20	5.08 (.200)	15.58 (.613)	18.30 (.720)	10.16 (.400)
28	7.62 (.300)	18.12 (.713)	21.86 (.860)	12.70 (.500)
32	7.62 (.300)	17.60 (.692)	23.00 (.905)	12.60 (.496)
44	12.70 (.500)	24.50 (.960)	30.04 (1.180)	17.78 (700)
52	15.24 (600)	27.00 (1.060)	32.64 (1.290)	20.32 (.800)
68	20.32 (.800)	32.00 (1.260)	39.70 (1.560)	25.40 (1.000)
84	25.40 (1.000)	37.10 (1.460)	46.90 (1.850)	30.48 (1.200)
100	31.75 (1.250)	42.26 (1.664)	54.10 (2.130)	35.56 (1.400)